

WHAT IS CLAIMED IS:

1. A laminated ceramic capacitor comprising:

a rectangular parallelepiped laminated chip having a plurality of first conductor layers and a plurality of second conductor layers, the first conductor layers and the second conductor layers being alternately arranged to face each other through a ceramic layer;

at least one first electrode which is provided on one face of the laminated chip and conducts with the first conductor layers;

at least one second electrode which is provided in the one face of the laminated chip without contacting with the first electrode, and conducts with the second conductor layers; and

at least one heat radiation conductor which is provided on at least one face different from the one face of the laminated chip, and conducts with at least one of the first conductor layers and the second conductor layers.

2. The laminated ceramic capacitor according to claim 1, wherein the heat radiation conductor consists of a conductive film formed on at least one face different from the one face of the laminated chip.

3. The laminated ceramic capacitor according to claim 1, wherein the heat radiation conductor consists of a conductive plate provided on at least one face different from the one face of the laminated chip.

4. The laminated ceramic capacitor according to claim 3, wherein the conductive plate has a concavity which accepts a part of the laminated chip.

5. The laminated ceramic capacitor according to claim 3, wherein

the conductive plate has a plurality of fins.

6. The laminated ceramic capacitor according to claim 1, wherein the heat radiation conductor consists of a conductive film formed on at least one face different from the one face of the laminated chip, and of a conductive plate connected to the conductive film.

7. The laminated ceramic capacitor according to claim 6, wherein the conductive plate has a concavity which accepts a part of the laminated chip.

8. The laminated ceramic capacitor according to claim 6, wherein the conductive plate has a plurality of fins.

9. The laminated ceramic capacitor according to claim 1, wherein the heat radiation conductor is provided on a face opposite to the one face of the laminated chip.

10. The laminated ceramic capacitor according to claim 1, wherein the heat radiation conductor is provided on at least one face adjacent to the one face of the laminated chip.

11. The laminated ceramic capacitor according to claim 1, wherein the heat radiation conductor is provided on a face opposite to the one face of the laminated chip and at least one face adjacent to this face.

12. The laminated ceramic capacitor according to claim 1, wherein the number of the heat radiation conductors is one, and one of the first conductor layers and the second conductor layers conduct with the heat

radiation conductor.

13. The laminated ceramic capacitor according to claim 1, wherein the number of the heat radiation conductors is two, the first conductor layers conduct with one of the heat radiation conductors, and the second conductor layers conduct with another one of the heat radiation conductors.

14. The laminated ceramic capacitor according to claim 1, wherein at least one of the first electrode and the second electrode has a rounding portion which extends at least one face adjacent to the one face.

15. A mounted structure comprising:

at least one laminated ceramic capacitor mounted on a substrate so that a first electrode of the laminated ceramic capacitor is connected to a first land on a mounting surface of the substrate and a second electrode of the laminated ceramic capacitor is connected to a second land on the mounting surface of the substrate,

wherein the laminated capacitor includes,

a rectangular parallelepiped laminated chip having a plurality of first conductor layers and a plurality of second conductor layers, the first conductor layers and the second conductor layers being alternately arranged to face each other through a ceramic layer;

at least one first electrode which is provided on one face of the laminated chip and conducts with the first conductor layers;

at least one second electrode which is provided in the one face of the laminated chip without contacting with the first electrode, and conducts with the second conductor layers; and

at least one heat radiation conductor which is provided on at least one face different from the one face of the laminated chip, and conducts with at least one of the first conductor layers and the second conductor layers.

16. The mounted structure according to claim 15, wherein the heat radiation conductor consists of a conductive film formed on at least one face different from the one face of the laminated chip.

17. The mounted structure according to claim 15, wherein the heat radiation conductor consists of a conductive plate provided on at least one face different from the one face of the laminated chip.

18. The mounted structure according to claim 17, wherein the conductive plate has a concavity which accepts a part of the laminated chip.

19. The mounted structure according to claim 17, wherein the conductive plate has a plurality of fins.

20. The mounted structure according to claim 17, wherein plural the laminated capacitors are mounted on the substrate, and the laminated capacitors hold the conductive plate in common.

21. The mounted structure according to claim 15, wherein the heat radiation conductor consists of a conductive film formed on at least one face different from the one face of the laminated chip, and of a conductive plate connected to the conductive film.

22. The mounted structure according to claim 21, wherein the conductive plate has a concavity which accepts a part of the laminated chip.

23. The mounted structure according to claim 21, wherein the conductive plate has a plurality of fins.

24. The mounted structure according to claim 21, wherein plural the laminated capacitors are mounted on the substrate, and the laminated capacitors hold the conductive plate in common.

25. A capacitor module comprising:

a conductive plate with a predetermined shape; and
a plurality of laminated ceramic capacitors including, a rectangular parallelepiped laminated chip having a plurality of first conductor layers and a plurality of second conductor layers, the first conductor layers and the second conductor layers being alternately arranged to face each other through a ceramic layer; at least one first electrode which is provided on one face of the laminated chip and conducts with the first conductor layers; at least one second electrode which is provided in the one face of the laminated chip without contacting with the first electrode, and conducts with the second conductor layers; and at least one heat radiation conductor which is provided on at least one face different from the one face of the laminated chip, and conducts with at least one of the first conductor layers and the second conductor layers,

wherein the capacitor module is constituted by providing each laminated ceramic capacitor on the conductive plate in predetermined arrangement so that a face different from the one face of each laminated

chip faces the conductive plate, and at least one of the first conductor layers and second conductor layers conduct with the conductive plate.

26. The capacitor module according to claim 25, wherein the conductive plate has a plurality of concavities that respectively accept a part of the laminated chip of each the laminated ceramic capacitor.

27. The capacitor module according to claim 25, wherein the conductive plate has a plurality of fins.